

# Complementary Silicon Plastic Power Transistors

## DPAK-3 for Surface Mount Applications

### MJD243 (NPN), MJD253 (PNP)

Designed for low voltage, low-power, high-gain audio amplifier applications.

#### Features

- High DC Current Gain
- Lead Formed for Surface Mount Applications in Plastic Sleeves (No Suffix)
- Straight Lead Version in Plastic Sleeves ("–1" Suffix)
- Low Collector–Emitter Saturation Voltage
- High Current–Gain – Bandwidth Product
- Annular Construction for Low Leakage
- Epoxy Meets UL 94 V–0 @ 0.125 in
- NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

#### MAXIMUM RATINGS

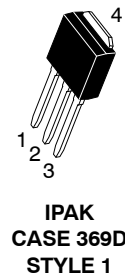
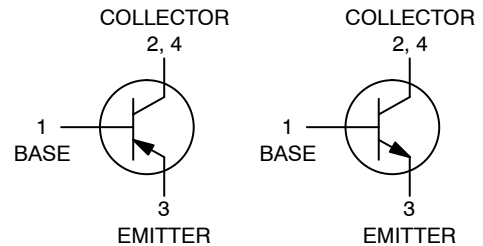
Rating	Symbol	Value	Unit
Collector–Base Voltage	$V_{CB}$	100	Vdc
Collector–Emitter Voltage	$V_{CEO}$	100	Vdc
Emitter–Base Voltage	$V_{EB}$	7.0	Vdc
Collector Current – Continuous	$I_C$	4.0	Adc
Collector Current – Peak	$I_{CM}$	8.0	Adc
Base Current	$I_B$	1.0	Adc
Total Device Dissipation @ $T_C = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	12.5 0.1	W W/ $^\circ\text{C}$
Total Device Dissipation @ $T_A = 25^\circ\text{C}$ (Note 2) Derate above $25^\circ\text{C}$	$P_D$	1.4 0.011	W W/ $^\circ\text{C}$
Operating and Storage Junction Temperature Range	$T_J, T_{stg}$	–65 to +150	$^\circ\text{C}$
ESD – Human Body Model	HBM	3B	V
ESD – Machine Model	MM	C	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

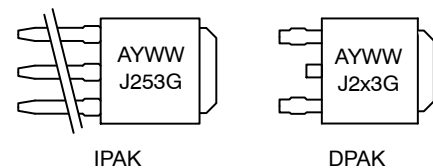
1. When surface mounted on minimum pad sizes recommended.

## 4.0 A, 100 V, 12.5 W POWER TRANSISTOR

#### COMPLEMENTARY



#### MARKING DIAGRAM



A = Assembly Location  
Y = Year  
WW = Work Week  
x = 4 or 5  
G = Pb–Free Package

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

NOTE: Some of the device on this data sheet have been **DISCONTINUED**. Please refer to the table on page 6.

# MJD243 (NPN), MJD253 (PNP)

## THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance Junction-to-Case Junction-to-Ambient (Note 2)	$R_{\theta JC}$ $R_{\theta JA}$	10 89.3	$^{\circ}\text{C/W}$

2. When surface mounted on minimum pad sizes recommended.

## ELECTRICAL CHARACTERISTICS ( $T_C = 25^{\circ}\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
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### OFF CHARACTERISTICS

Collector-Emitter Sustaining Voltage (Note 3) ( $I_C = 10 \text{ mAdc}$ , $I_B = 0$ )	$V_{CE(sus)}$	100	–	Vdc
Collector Cutoff Current ( $V_{CB} = 100 \text{ Vdc}$ , $I_E = 0$ ) ( $V_{CB} = 100 \text{ Vdc}$ , $I_E = 0$ , $T_J = 125^{\circ}\text{C}$ )	$I_{CBO}$	– –	100 100	nAdc $\mu\text{Adc}$
Emitter Cutoff Current ( $V_{BE} = 7.0 \text{ Vdc}$ , $I_C = 0$ )	$I_{EBO}$	–	100	nAdc
DC Current Gain (Note 3) ( $I_C = 200 \text{ mAdc}$ , $V_{CE} = 1.0 \text{ Vdc}$ ) ( $I_C = 1.0 \text{ Adc}$ , $V_{CE} = 1.0 \text{ Vdc}$ )	$h_{FE}$	40 15	180 –	–
Collector-Emitter Saturation Voltage (Note 3) ( $I_C = 500 \text{ mAdc}$ , $I_B = 50 \text{ mAdc}$ ) ( $I_C = 1.0 \text{ Adc}$ , $I_B = 100 \text{ mAdc}$ )	$V_{CE(sat)}$	– –	0.3 0.6	Vdc
Base-Emitter Saturation Voltage (Note 3) ( $I_C = 2.0 \text{ Adc}$ , $I_B = 200 \text{ mAdc}$ )	$V_{BE(sat)}$	–	1.8	Vdc
Base-Emitter On Voltage (Note 3) ( $I_C = 500 \text{ mAdc}$ , $V_{CE} = 1.0 \text{ Vdc}$ )	$V_{BE(on)}$	–	1.5	Vdc

### DYNAMIC CHARACTERISTICS

Current-Gain – Bandwidth Product (Note 4) ( $I_C = 100 \text{ mAdc}$ , $V_{CE} = 10 \text{ Vdc}$ , $f_{test} = 10 \text{ MHz}$ )	$f_T$	40	–	MHz
Output Capacitance ( $V_{CB} = 10 \text{ Vdc}$ , $I_E = 0$ , $f = 0.1 \text{ MHz}$ )	$C_{ob}$	–	50	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulse Test: Pulse Width = 300  $\mu\text{s}$ , Duty Cycle  $\approx 2\%$ .

4.  $f_T = |h_{FE}| \cdot f_{test}$ .

## MJD243 (NPN), MJD253 (PNP)

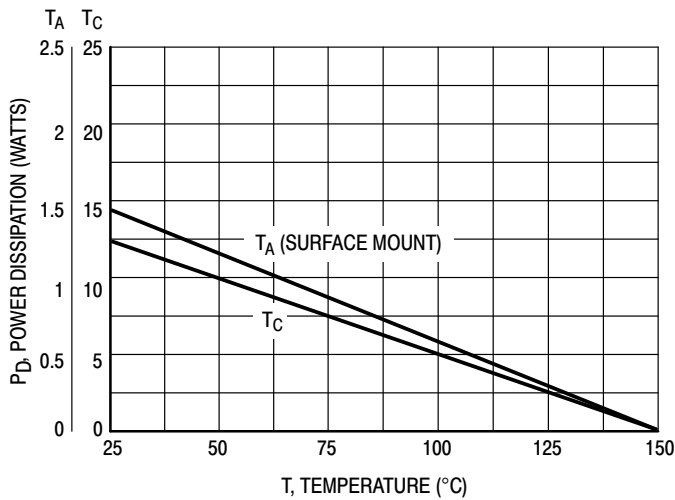


Figure 1. Power Derating

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate  $I_C - V_{CE}$  limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

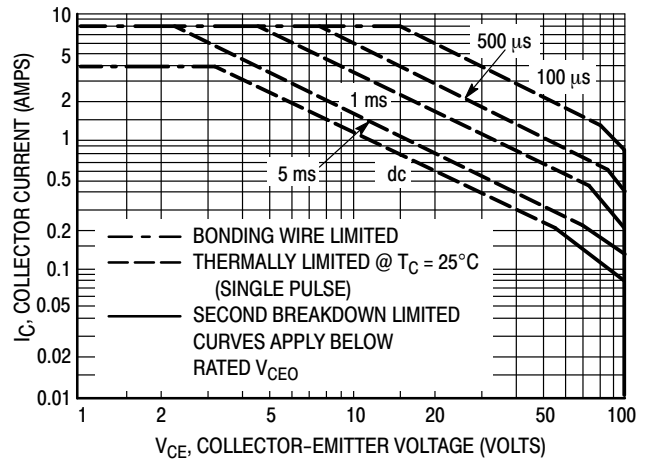


Figure 2. Active Region Maximum Safe Operating Area

The data of Figure 2 is based on  $T_{J(pk)} = 150^\circ\text{C}$ ;  $T_C$  is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided  $T_{J(pk)} \leq 150^\circ\text{C}$ .  $T_{J(pk)}$  may be calculated from the data in Figure 3. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

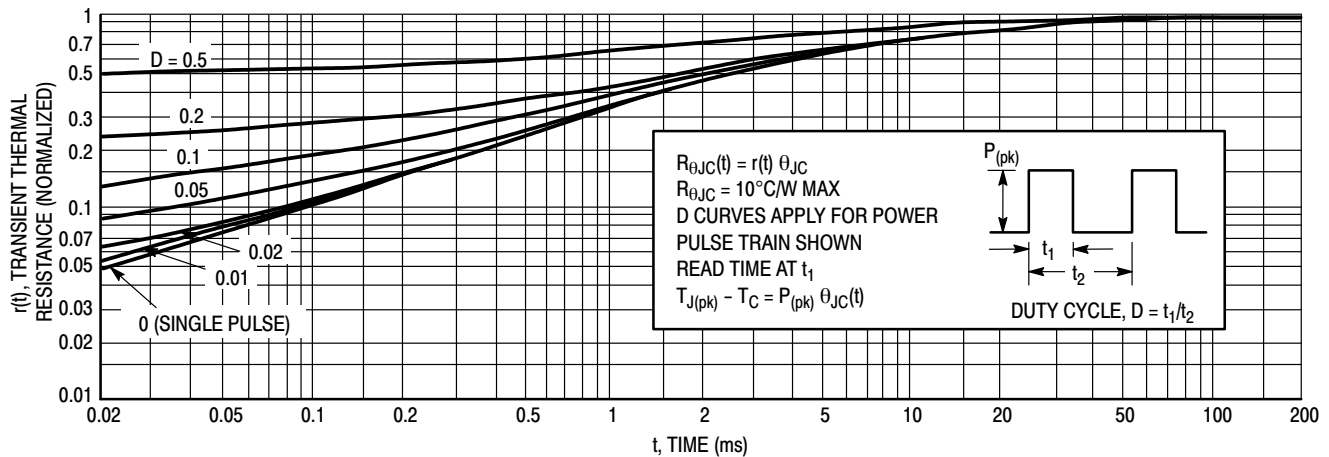
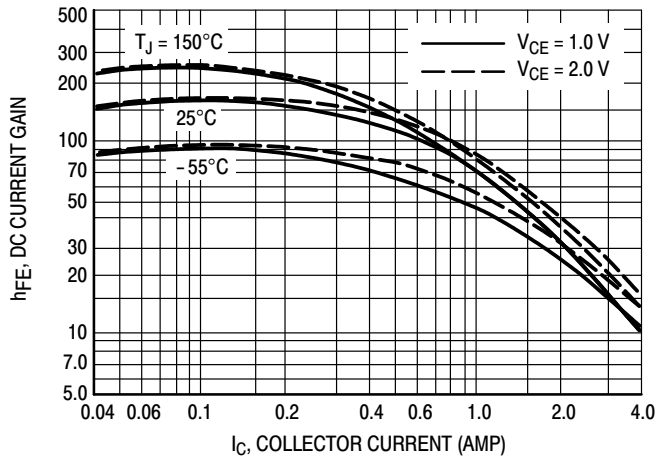


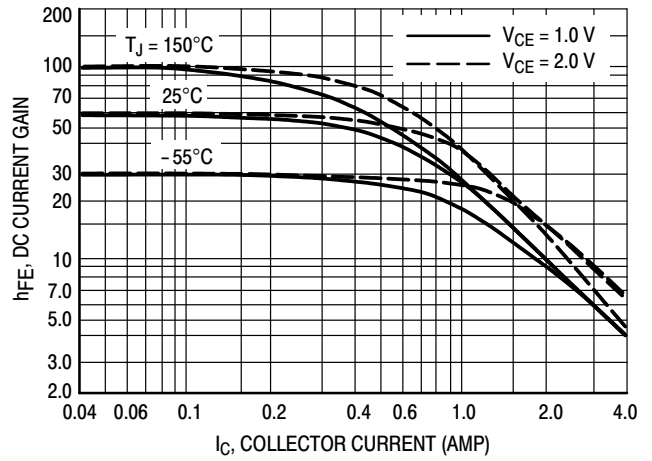
Figure 3. Thermal Response

# MJD243 (NPN), MJD253 (PNP)

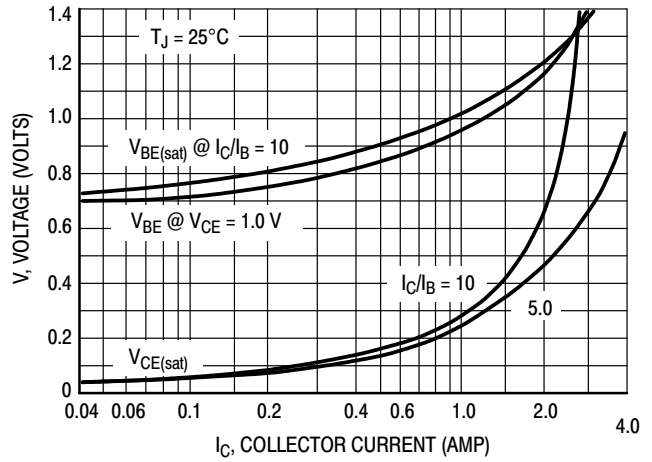
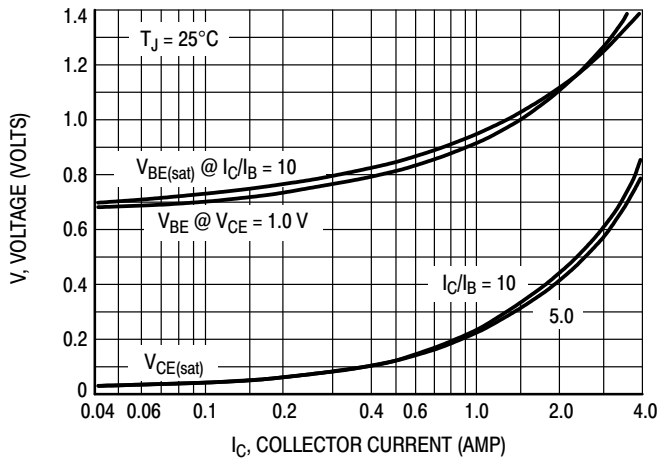
**NPN  
MJD243**



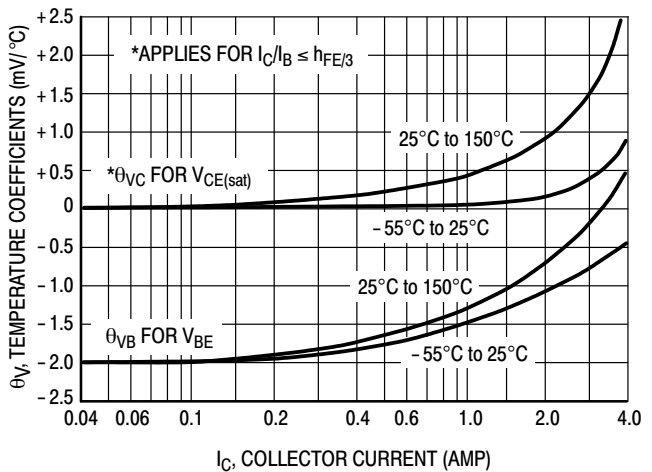
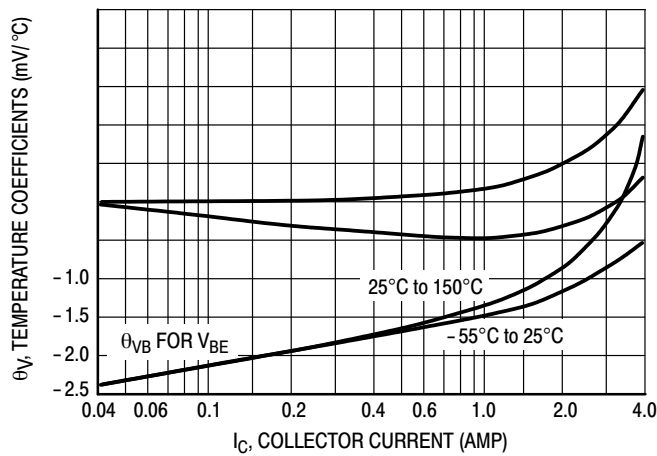
**PNP  
MJD253**



**Figure 4. DC Current Gain**



**Figure 5. "On" Voltages**



**Figure 6. Temperature Coefficients**

## MJD243 (NPN), MJD253 (PNP)

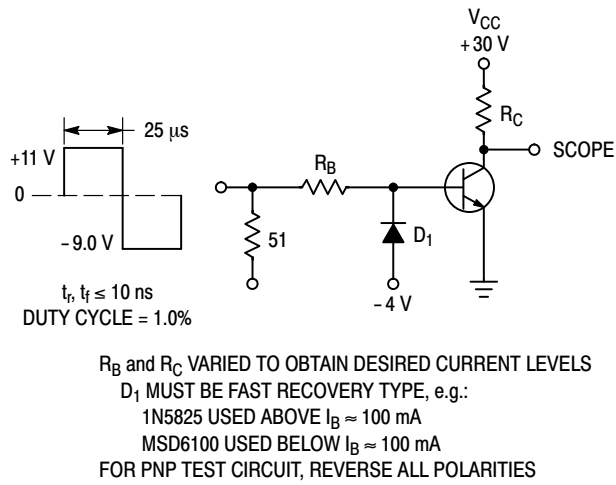


Figure 7. Switching Time Test Circuit

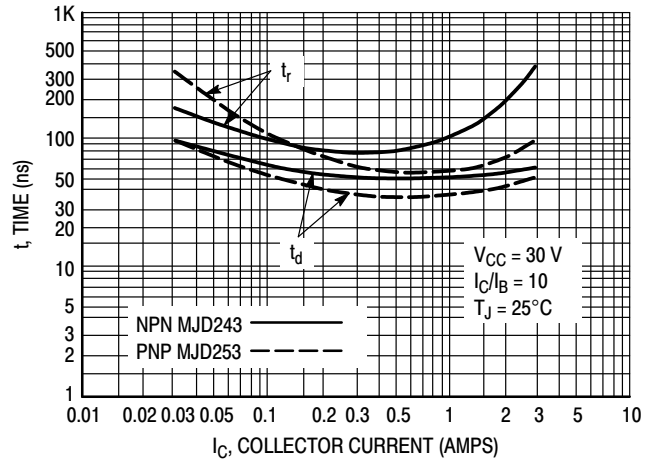


Figure 8. Turn-On Time

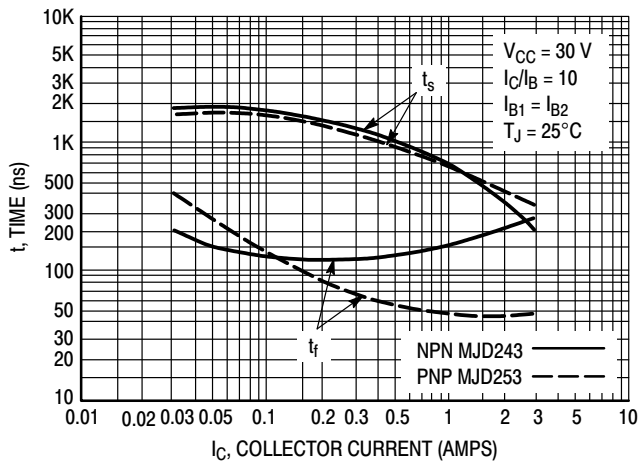


Figure 9. Turn-Off Time

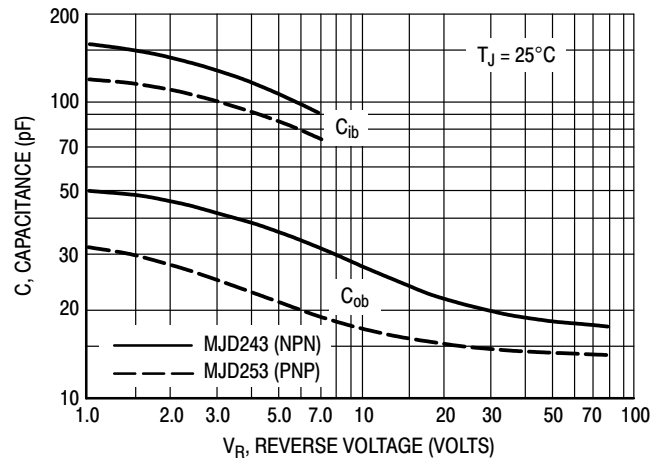


Figure 10. Capacitance

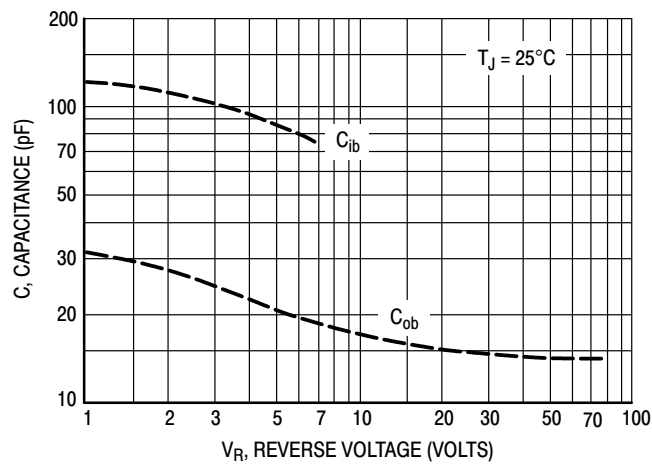


Figure 11. Capacitance

## MJD243 (NPN), MJD253 (PNP)

### ORDERING INFORMATION

Device	Package Type	Package	Shipping <sup>†</sup>
MJD243G	DPAK-3 (Pb-Free)	369C	75 Units / Rail
MJD243T4G	DPAK-3 (Pb-Free)	369C	2,500 / Tape & Reel
NJVMJD243T4G*	DPAK-3 (Pb-Free)	369C	2,500 / Tape & Reel
MJD253T4G	DPAK-3 (Pb-Free)	369C	2,500 / Tape & Reel
NJVMJD253T4G*	DPAK-3 (Pb-Free)	369C	2,500 / Tape & Reel

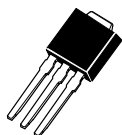
### DISCONTINUED (Note 5)

Device	Package Type	Package	Shipping <sup>†</sup>
MJD253-1G	IPAK (Pb-Free)	369D	75 Units / Rail

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

5. **DISCONTINUED:** This device is not recommended for new design. Please contact your **onsemi** representative for information. The most current information on this device may be available on [www.onsemi.com](http://www.onsemi.com).

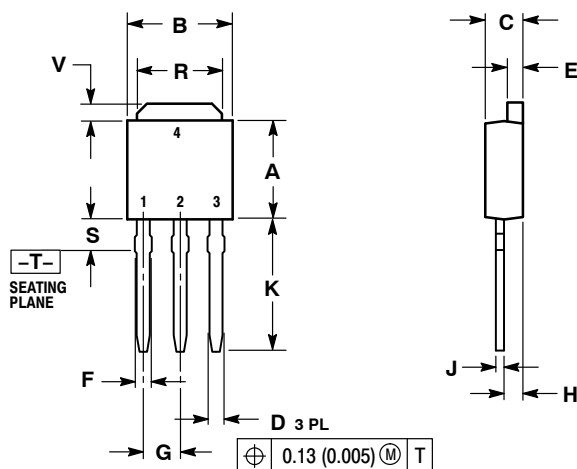
\*NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable



DPAK INSERTION MOUNT  
CASE 369  
ISSUE O

DATE 02 JAN 2000

SCALE 1:1



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.235	0.250	5.97	6.35
B	0.250	0.265	6.35	6.73
C	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
E	0.033	0.040	0.84	1.01
F	0.037	0.047	0.94	1.19
G	0.090 BSC		2.29 BSC	
H	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.350	0.380	8.89	9.65
R	0.175	0.215	4.45	5.46
S	0.050	0.090	1.27	2.28
V	0.030	0.050	0.77	1.27

STYLE 1:  
PIN 1. BASE  
2. COLLECTOR  
3. EMITTER  
4. COLLECTOR

STYLE 2:  
PIN 1. GATE  
2. DRAIN  
3. SOURCE  
4. DRAIN

STYLE 3:  
PIN 1. ANODE  
2. CATHODE  
3. ANODE  
4. CATHODE

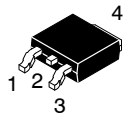
STYLE 4:  
PIN 1. CATHODE  
2. ANODE  
3. GATE  
4. ANODE

STYLE 5:  
PIN 1. GATE  
2. ANODE  
3. CATHODE  
4. ANODE

STYLE 6:  
PIN 1. MT1  
2. MT2  
3. GATE  
4. MT2

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DESCRIPTION:	DPAK INSERTION MOUNT	PAGE 1 OF 1

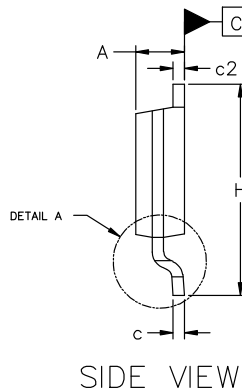
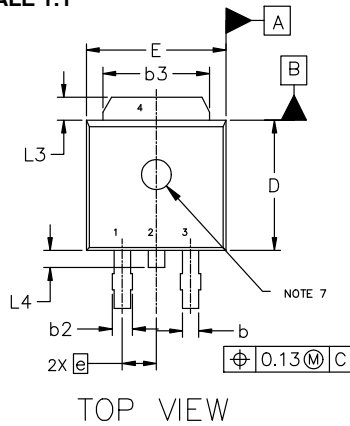
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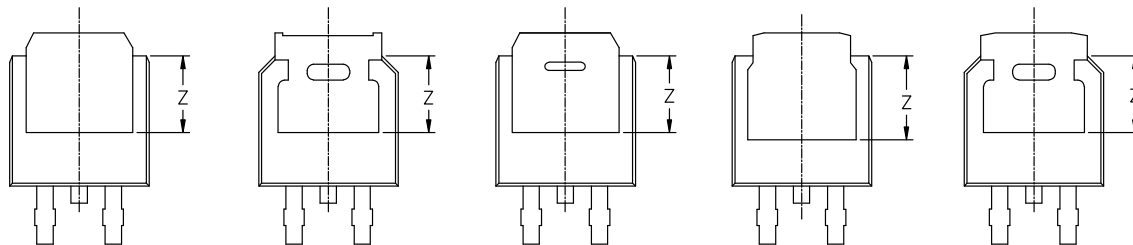
DPAK3 6.10x6.54x2.28, 2.29P  
CASE 369C  
ISSUE J

DATE 12 AUG 2025

SCALE 1:1

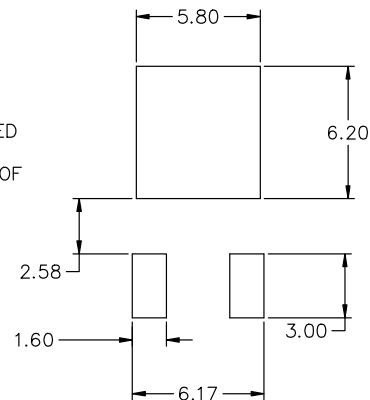
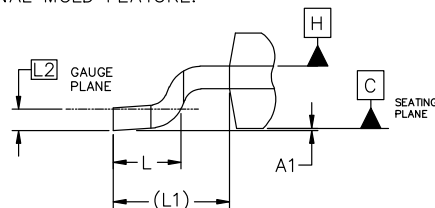


MILLIMETERS			
DIM	MIN	NOM	MAX
A	2.18	2.28	2.38
A1	0.00	---	0.13
b	0.63	0.76	0.89
b2	0.72	0.93	1.14
b3	4.57	5.02	5.46
c	0.46	0.54	0.61
c2	0.46	0.54	0.61
D	5.97	6.10	6.22
E	6.35	6.54	6.73
e	2.29 BSC		
H	9.40	9.91	10.41
L	1.40	1.59	1.78
L1	2.90 REF		
L2	0.51 BSC		
L3	0.89	---	1.27
L4	---	---	1.01
Z	3.93	---	---



NOTES:

1. DIMENSIONING AND TOLERANCING ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3, AND Z.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15mm PER SIDE.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.
7. OPTIONAL MOLD FEATURE.



RECOMMENDED MOUNTING FOOTPRINT\*

\*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERM/D.

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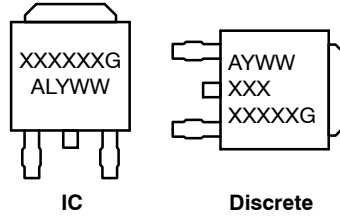
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DPAK3 6.10x6.54x2.28, 2.29P  
CASE 369C  
ISSUE J

DATE 12 AUG 2025

GENERIC  
MARKING DIAGRAM\*



XXXXXX = Device Code  
A = Assembly Location  
L = Wafer Lot  
Y = Year  
WW = Work Week  
G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

STYLE 1: PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR	STYLE 2: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN	STYLE 3: PIN 1. ANODE 2. CATHODE 3. ANODE 4. CATHODE	STYLE 4: PIN 1. CATHODE 2. ANODE 3. GATE 4. ANODE	STYLE 5: PIN 1. GATE 2. ANODE 3. CATHODE 4. ANODE
STYLE 6: PIN 1. MT1 2. MT2 3. GATE 4. MT2	STYLE 7: PIN 1. GATE 2. COLLECTOR 3. EMITTER 4. COLLECTOR	STYLE 8: PIN 1. N/C 2. CATHODE 3. ANODE 4. CATHODE	STYLE 9: PIN 1. ANODE 2. CATHODE 3. RESISTOR ADJUST 4. CATHODE	STYLE 10: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. ANODE

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